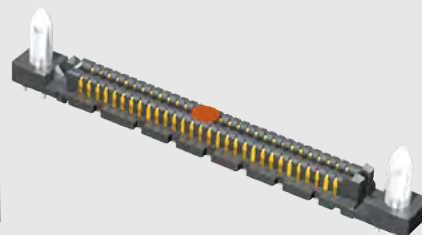


SEAM-20-01-L-06-2-RA-GP-TR



SEAM-30-02.0-L-04-2-A-GP-K-TR

(1.27 mm) .050"

SEAM-RA, SEAM-GP SERIES

HI-DENSITY RIGHT-ANGLE OPEN-PIN-FIELD

SEAM-RA Mates with:
SEAF, SEAF-RA, SEAFP

SEAM-GP Mates with:
SEAF-RA-GP

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAM-RA or www.samtec.com?SEAM

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Current Rating:

SEAM-RA = 2.0 A per pin
(6 adjacent pins powered)

Operating Temp Range:
-55 °C to +125 °C

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Contact Resistance:

SEAM-RA = 19 mΩ

SEAM-GP = 5.5 mΩ

Working Voltage:

SEAM-RA = 260 VAC

SEAM-GP = 240 VAC

Mated Cycles:

SEAM-GP = 100

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

SEAM	NO. PINS PER ROW	01	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTION	TR
	-20, -30, -40, -50		-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows -06 = Six Rows -08* = Eight Rows -10* = Ten Rows	-1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge		-GP = Guide Post -K = Polyimide film Pick & Place Pad	-TR = Tape & Reel

*Note: Fixturing required to process eight and ten row options, see www.samtec.com/searayfixture

NO. PINS PER ROW	A
-20	(38.94) 1.533
-30	(51.64) 2.033
-40	(64.34) 2.533
-50	(77.04) 3.03

-GP= No. of positions x (1.27) .050 + (19.56) 0.77
 Without -GP= No. of positions x (1.27) .050 + (11.18) 0.44
 A
 (5.36) .211
 (3.05) .120 DIA
 (1.27) .050
 (8.13) .320
 (12.32) .485
 (7.91) .312
 (1.60) .063
 (0.64) .025

HIGH-SPEED CHANNEL PERFORMANCE

SEAM-RA/SEAF-RA

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

25
G b p s

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

SEAM	NO. PINS PER ROW	02.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	GP	K	TR
	-20, -30, -40, -50		-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows -06 = Six Rows -08 = Eight Rows -10 = Ten Rows	-1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge			-K = Polyimide film Pick & Place Pad -TR = Tape & Reel (Not available with 50 positions)	

No. of positions x (1.27) .050 + (19.46) .766
 (3.05) .120 DIA
 (5.54) .218
 (4.60) .181
 (1.27) .050
 (1.12) .044 DIA
 (0.86) .034 DIA
 No. of positions x (1.27) .050 + (3.58) .141
 (1.27) .050
 (0.51) .020 SQ
 (1.02) .040
 (8.13) .320
 (12.65) .498

ALSO AVAILABLE (MOQ Required)

- Extended Guide Post
 - Guide post field termination kits
 - Other platings
- Contact Samtec.

Note: SEAM-GP Patented

Note: Some sizes, styles and options are non-standard, non-returnable.